| SPEC. NO.: | PS-53007-XXXXX-XXX | |
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PRODUCT NAME: 2.00mm BATTERY CONN. R/A TYPE

PRODUCT NO: 53001,53002, 53003, 53004, 53007, 53008,53050,

53049 SERIES

| PREPARED: | CHECKED: | APPROVED: |
|---------------------|---------------------|---------------------|
| FENGXIAO | CARL | JASON |
| DATE: 2013.07.30 | DATE: 2013.07.30 | DATE: 2013.07.30 |

| | Aces | P/N: 53007 SERIES | | | | | |
|-------------------------------------------------------------------------------------------|---------------------------------------------------|-------------------|----------------------------|--|--|--|--|
| TITLE: 2.00mm BATTERY CONN. R/A TYPE | | | | | | | |
| RELEASE DATE: 2013/07/30 | REVISION: 0 | ECN No: 1307482 | PAGE: 2 OF 9 | | | | |
| 1 REVISION HIS 2 SCOPE 3 APPLICABLE 4 REQUIREMEN 5 PERFORMAN 6 INFRARED RE | STORY DOCUMENTS ITS CE FLOW CONDITION | TEST SEQUENCE | | | | | |

Aces P/N: 53007 SERIES
TITLE: 2.00mm BATTERY CONN. R/A TYPE

REVISION: 0

RELEASE DATE: 2013/07/30

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1 Revision History

| Rev. | ECN # | Revision Description | Prepared | Date |
|------|-------------|-----------------------|----------|------------|
| 1 | ECN-1111001 | NEW DRAW FOR 53007 | BRAVE | 2011/10/13 |
| 2 | ECN-1212162 | ADD 53050,53049SERIES | XHX | 2012/12/17 |
| 0 | ECN-1307482 | RELEASE | FNEGXIAO | 2013/07/30 |
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| Aces P/N: 53007 SERIES | | | | | | | |
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| TITLE: 2.00mm BATTERY CONN. R/A TYPE | | | | | | | |
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| 2 SCOPE | oovoro porformanao 1 | tests and quality requirement | s for 2 00mm pitch | | | | |

This specification covers performance, tests and quality requirements for 2.00mm pitch Battery Conn. R/A Type.

3 APPLICABLE DOCUMENTS

EIA-364 : ELECTRONICS INDUSTRIES ASSOCIATION

4 REQUIREMENTS

4.1 Design and Construction

- 4.1.1 Connector shall be of the design, construction and physical dimensions specified on the applicable sales drawing.
- 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.

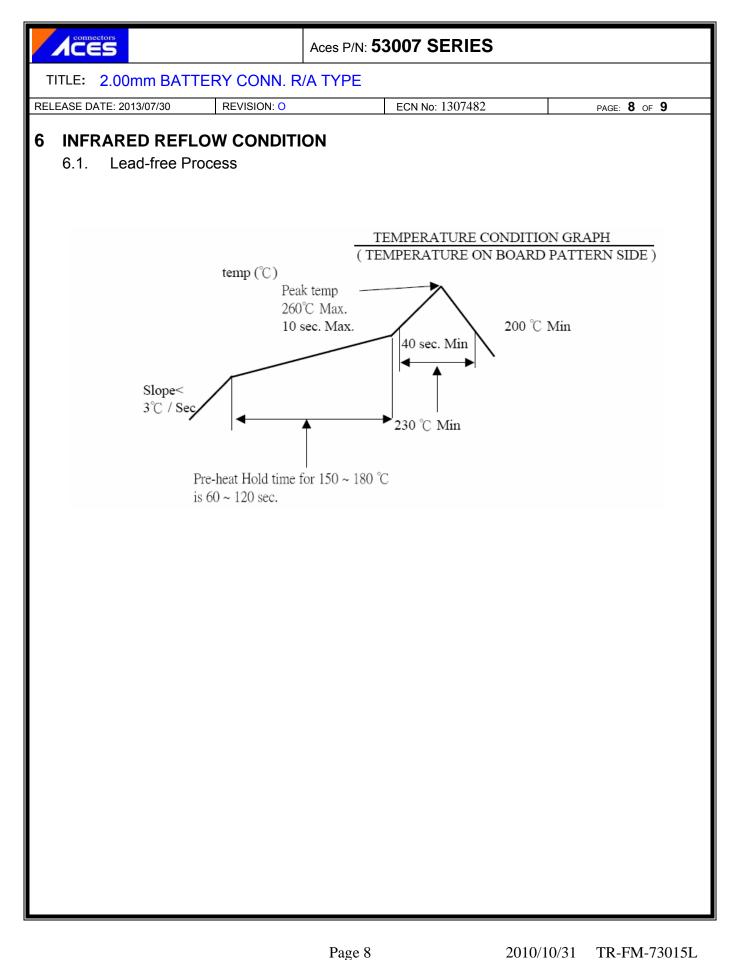
4.2 Materials and Finish

- 4.2.1 Contact: High performance copper alloy Finish: Pls. refer to the drawing.
 - 4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0
 - 4.2.3 Board Lock: High performance copper alloy
 - Finish: Pls. refer to the drawing.
 - 4.2.4 Screw: High performance copper alloy Finish: Pls. refer to the drawing.
- 4.3 Ratings
 - 4.3.1 Voltage: 30V AC, DC
 - 4.3.2 Current: 5.0A AC, DC (per pin)
 - 4.3.3 Operating Temperature : -40 $^\circ\!\mathrm{C}$ to +85 $^\circ\!\mathrm{C}$

| DATE: 0010/07/20 | | CN No: 1307482 | F | | | |
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| erformance | | | | | | |
| . Test Requirement | s and Procedures Summary | | | | | |
| Item | Requirement | Stand | ard | | | |
| | Product shall meet | Visual, dimensiona | l and functional | | | |
| Examination of Proc | luct requirements of applicab | | ity inspection | | | |
| | product drawing and | plan. | | | | |
| | specification. | <u>ا ۸ ا</u> | | | | |
| ltem | Requirement | AL Stand | ard | | | |
| | Requirement | | | | | |
| | | Mate connectors, | measure by dry | | | |
| Low Level | Initial: 20 m Ω Max. | circuit, 20mV Max., | , <u>,</u> | | | |
| Contact Resistance | After test: 40 m Ω Max. | Max. | | | | |
| | | (EIA-364-23) | (EIA-364-23) | | | |
| | | Unmated connecto | rs. apply | | | |
| Inculation Desistant | | | 500 V DC between adjacent | | | |
| Insulation Resistance | ce 500 M Ω Min. | terminals. | | | | |
| | | (EIA-364-21) | | | | |
| Dielectric | | 500 V AC Min. at s | | | | |
| Withstanding Voltag | e No breakdown. | minute. Test betwe contacts of unmate | | | | |
| | | (EIA-364-20) | u connectors. | | | |
| | | | | | | |
| | | Mate connector: me temperature rise at | | | | |
| Temperature rise | 30°C Max.Change allowe | | | | | |
| r omporataro noo | | ambient condition i | | | | |
| | | (EIA-364-70,METH | | | | |
| | | CONDITION1) | , | | | |
| | MECHANIC | CAL | | | | |
| ltem | Requirement | Stand | ard | | | |
| | Mating Earoa: | Operation Speed : | | | | |
| Mating /Unmating | Mating Force: 0.25kgf Max / per pin | Operation Speed : | 2 | | | |
| Forces | Unmating Force: | 25.4 ± 3 mm/minut Measure the force | | | | |
| | 0.02kgf Min / per pin | mate/unmated con | | | | |
| | | (EIA-364-13) | | | | |
| | | (EIA-364-13) | | | | |

| | Aces P | P/N: 53007 SERIES | |
|----------------------------|--------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| LE: 2.00mm BATTER | RY CONN. R/A TYP | ΡE | |
| ASE DATE: 2013/07/30 | REVISION: O | ECN No: 1307482 | PAGE: 6 OF 9 |
| Contact Retention Force | 0.4kgf Min | Operation Speed 25.4 ± 3 mm/min Measure the con with Tensile stre | ute. tact retention force |
| Lock Retention Force | <mark>0.35kgf</mark> Min | Operation Speed 25.4 ± 3 mm/min Measure the con with Tensile stre | ute. tact retention force |
| Durability | 5000 cycles. | The sample shou the tester and fu unmated the nur specified at the r 3mm/min. | nber of cycles |
| Vibration | 1 µs Max. | be 100 mA maxi contacts. Subject harmonic motion of 0.76mm (1.52 total excursion) i between the limi The entire freque 10 to 55 Hz and shall be traverse 1 minute. This n applied for 2 hou | ct to a simple having amplitude mm maximum n frequency ts of 10 and 55 Hz. ency range, from return to 10 Hz, d in approximately notion shall be irs in each of three dicular directions. |
| Shock (Mechanical) | 1 µs Max. | Subject mated c 50G's(peak valu pulses of 11 milli Three shocks in | onnectors to e) half-sine shock iseconds duration. each direction shall the three mutually tes of the test ocks). The ondition shall be for all contacts. |

Aces P/N: 53007 SERIES TITLE: 2.00mm BATTERY CONN. R/A TYPE RELEASE DATE: 2013/07/30 REVISION: 0 ECN No: 1307482 PAGE: 7 OF 9 ENVIRONMENTAL See Product Qualification Solder Temp. : and Test Sequence Group Resistance to Wave 265±5°C, 10±0.5sec. 10 (Lead Free) Soldering Heat Pre Heat : 150°C ~180°C, Resistance to Reflow See Product Qualification 60~120sec. Soldering Heat and Test Sequence Group Heat : 230°C Min., 40sec Min. 10 (Lead Free) Peak Temp. : 260°C Max, 10sec Max. Hand Soldering $T \ge 350^{\circ}$ C, 3sec at least. Appearance: No damage Temperature Resistance Mate module and subject to follow condition for 5 cycles. See Product Qualification 1 cycles: Thermal Shock and Test Sequence Group -55+0/-3 °C, 30 minutes +85 +3/-0 $^\circ\!\mathrm{C}$, 30 minutes (EIA-364-32, test condition I) Mated Connector 40°C, 90~95% RH, See Product Qualification Humidity and Test Sequence Group 4 96 hours. (EIA-364-31, Condition A, Method II) Subject mated connectors to See product Qualification temperature life at 85°C for 96 hours. Temperature life (EIA-364-17, Test condition A) and test sequence group5 Subject mated/unmated connectors to 5% salt-solution See Product Qualification concentration, 35°C Salt Sprav and Test Sequence Group (Only For Gold Plating) (I) Gold flash for 8 hours (II) Gold plating 5 u" for 96 hours. (EIA-364-26) Tin plating: Solder able area shall have minimum of 95% solder And then into solder bath, coverage. Solder ability Temperature at $245 \pm 5^{\circ}$ C, for 4-5 Gold plating: sec. Solder able area shall have (EIA-364-52) minimum of 75% solder coverage Note. Flowing Mixed Gas shell be conduct by customer request.



| ICES | Aces | P/N: | 5300 | 7 SE | | S | | | | | |
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| 7 PRODUCT QUALIFICATION AND TEST SEQUENCE | | | | | | | | | | | |
| Test Group | | | | | | | | | | | |
| Test or Examination | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 |
| | Test Sequence | | | | | | | | | | |
| Examination of Product | 1,3 | | | 1,7 | 1,6 | 1,4 | | | | 1,4 | |
| Low Level Contact Resistance | | 1,5 | 1,4 | 2,10 | 2,9 | 2,5 | | | | 2,5 | |
| Insulation Resistance | | | | 3,9 | 3,8 | | | | | | |
| Dielectric Withstanding Voltage | | | | 4,8 | 4,7 | | | | | | |
| Temperature Rise | 2 | | | | | | | | | | |
| Mating / Un-mating Forces | | 2,4 | | | | | | | | | |
| Contact Retention Force | | | | | | | | 1 | | | |
| Durability | | 3 | | | | | | | | | |
| Vibration | | | 2 | | | | | | | | |
| Shock(Mechanical) | | | 3 | | | | | | | | |
| Resistance to Soldering Heat | | | | | | | | | | 3 | |
| Thermal Shock | | | | 5 | | | | | | | |
| Humidity | | | | 6 | | | | | | | |
| Temperature Life | | | | | 5 | | | | | | |
| Salt Spray(Only For Gold Plating) | | | | | | 3 | | | | | |
| Solder ability | | | | | | | 1 | | | | |
| Lock Retention Force | | | | | | | | | 1 | | |
| Hand Soldering Temperature Resistance | | | | | | | | | | | 1 |
| Sample Size | 2 | 4 | 4 | 4 | 4 | 4 | 2 | 4 | 4 | 4 | 4 |
| | | · | | <u>.</u> | | · | | | | · | |